

ABSTRACT

Provided is a method for producing a semiconductor device, which can reduce misalignment of a component to be bonded, such as a semiconductor chip. The
5 present invention relates to a method for producing a semiconductor device, including: a dry film formation step including drying a paste containing a metal and/or a metal oxide formed on a component A to be bonded, to form a dry film having a storage elastic modulus of 15 GPa or less; and a temporary bonding step including temporarily
10 bonding a component B to be bonded to the component A to be bonded via the dry film formed in the dry film formation step.

FIG.1